

TPD2E1B06 Dual-Channel High-Speed ESD Protection Device

1 Features

- Provides System Level ESD Protection for Low Voltage IO Interface
- IEC 61000-4-2 Level 4 ESD Rating
- Low IO Capacitance: 0.85 pF (Typical)
- DC Breakdown Voltage: 7 V (Minimum)
- Ultra-Low Leakage Current: 10 nA (Maximum)
- Low ESD Clamping Voltage
- Temperature Range: –40°C to 125°C
- Small Easy-to-Route DRL package

2 Applications

- Gaming Machines
- eBooks
- Portable Media Players
- Digital Cameras

3 Description

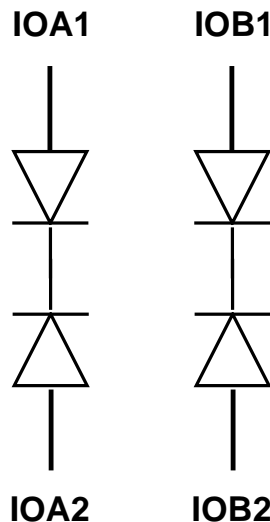
The TPD2E1B06 device is a dual-channel, ultra-low capacitance ESD protection device. It offers ± 10 -KV IEC contact ESD protection. Its 1-pF line capacitance makes it suitable for a wide range of applications. Typical application interfaces are USB 2.0, LVDS, and I2C. The TPD2E1B06 device has two common layout methods, and both are highlighted in [Layout](#).

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
TPD2E1B06	SOT (6)	1.60 mm x 1.20 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Schematic



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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision C (September 2013) to Revision D Page

- Added *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section. **1**

Changes from Revision B (September 2013) to Revision C Page

- Added air gap ESD specification to the ABSOLUTE MAXIMUM RATINGS table. **3**

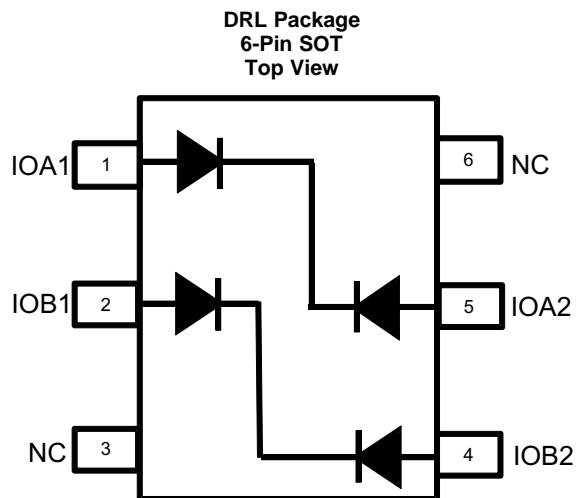
Changes from Revision A (August 2013) to Revision B Page

- Added TYPICAL CHARACTERISTICS section. **5**

Changes from Original (July 2013) to Revision A Page

- Revised document from PREVIEW to PRODUCTION DATA. **1**

5 Pin Configuration and Functions



Pin Functions

PIN		TYPE	DESCRIPTION	USAGE
NAME	NO.			
IOA1	1	I/O	ESD protected channel	See Application Information .
IOA2	5	I/O		
IOB1	2	I/O		
IOB2	4	I/O		
NC	3, 6	NC	No connect	Can be left floating, grounded, or connected to VCC

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
	Operating temperature	-40	125	°C
I_{PP}	Peak pulse current ($t_p = 8/20 \mu s$) ⁽²⁾		2.5	A
P_{PP}	Peak pulse power ($t_p = 8/20 \mu s$) ⁽²⁾		35	W
T_{stg}	Storage temperature	-65	155	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Using Routing Option 1 or 2 as shown in [Figure 13](#) or [Figure 14](#).

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	IEC 61000-4-2 contact discharge ⁽¹⁾	±10000	V
		IEC 61000-4-2 air-gap discharge ⁽¹⁾	±15000	

- (1) Using Routing Option 1 or 2 as shown in [Figure 13](#) or [Figure 14](#).

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{IO}	Pin IOA1 to IOA2; Pin IOB1 to IOB2	-5.5	5.5	V
T_A	Operating free-air temperature	-40	125	°C

6.4 Thermal Information

over operating free-air temperature range (unless otherwise noted)

THERMAL METRIC ⁽¹⁾		TPD2E1B06		UNIT
		DRL (SOT)		
		6 PINS		
$R_{\theta JA}$	Junction-to-ambient thermal resistance	349.7		°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	120.5		°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	171.4		°C/W
Ψ_{JT}	Junction-to-top characterization parameter	10.8		°C/W
Ψ_{JB}	Junction-to-board characterization parameter	169.4		°C/W

(1) For more information about traditional and new thermal metrics, the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

6.5 Electrical Characteristics

over operating free-air temperature range. (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{RWM}	Reverse standoff voltage				5.5	V
V_{CLAMP}	Clamp voltage with ESD strike	$I_{PP} = 1$ A, TLP, I/O to GND ⁽¹⁾⁽²⁾		11		V
		$I_{PP} = 5$ A, TLP, I/O to GND ⁽¹⁾⁽²⁾		15		
V_{CLAMP}	Clamp voltage with ESD strike	$I_{PP} = 1$ A, TLP, GND to I/O ⁽¹⁾⁽²⁾		11		V
		$I_{PP} = 5$ A, TLP, GND to I/O ⁽¹⁾⁽²⁾		15		
R_{DYN}	Dynamic resistance			0.9		Ω
C_{L1}	Pin 2 and 5 capacitance	Pin 1 and 4 = GND, $f = 1$ MHz, $V_{BIAS} = 2.5$ V ⁽²⁾⁽³⁾		0.85		pF
C_{L2}	Pin 1 and 4 capacitance	Pin 2 and 5 = GND, $f = 1$ MHz, $V_{BIAS} = 2.5$ V ⁽²⁾⁽⁴⁾		1.05		pF
V_{BR}	Break-down voltage	$I_{IO} = 1$ mA	7		9.5	V
I_{LEAK}	Leakage current	$V_{BIAS} = +2.5$ V		1	10	nA

(1) Transmission line pulse with rise time 10 ns and pulse width 100 ns.

(2) $T_A = 25^\circ\text{C}$

(3) Using Routing Option 1, [Figure 13](#).

(4) Using Routing Option 2, [Figure 14](#).

6.6 Typical Characteristics

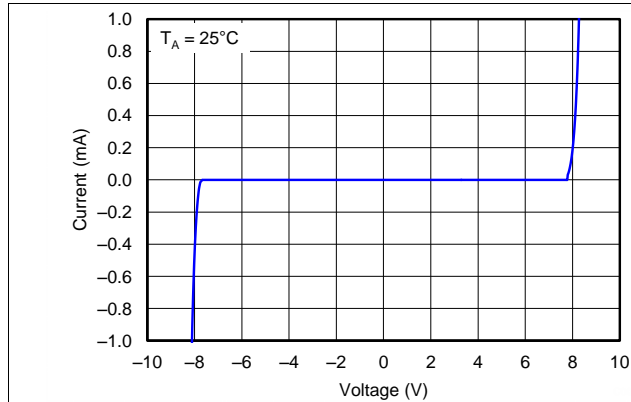


Figure 1. I_V Curve

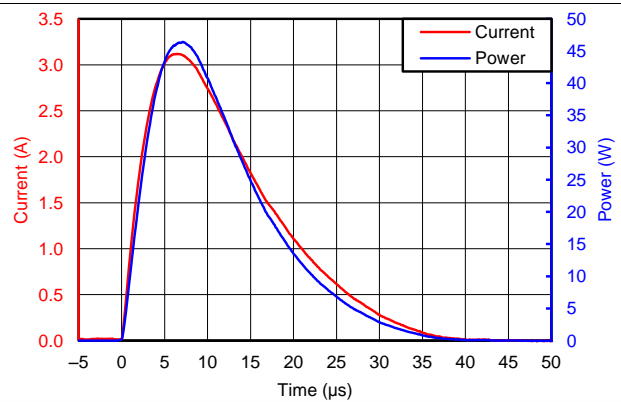


Figure 2. Maximum Surge Rating

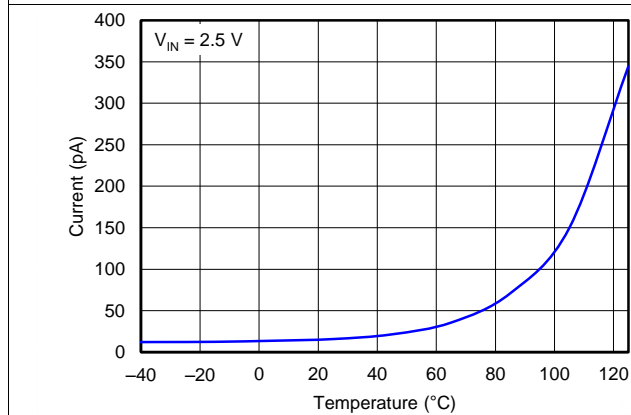


Figure 3. I_{LEAK} vs Temperature

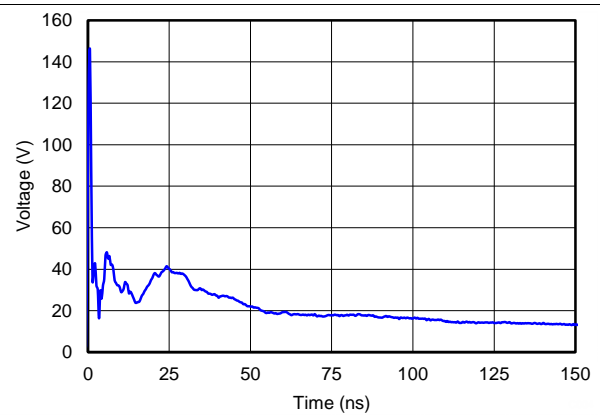


Figure 4. +8-kV Contact ESD Clamping

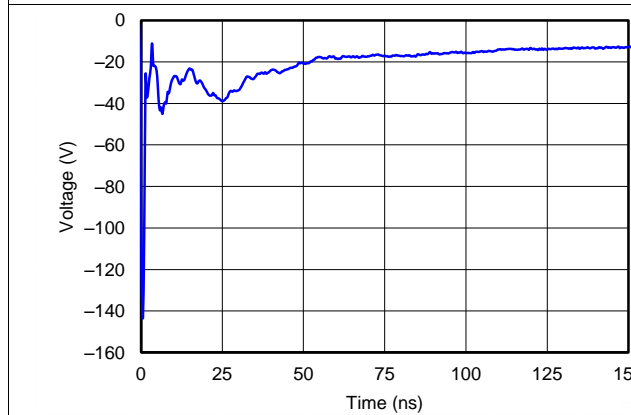


Figure 5. -8-kV Contact ESD Clamping

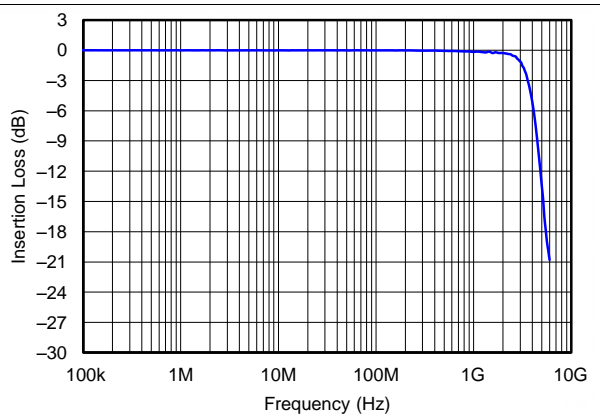


Figure 6. Insertion Loss

Typical Characteristics (continued)

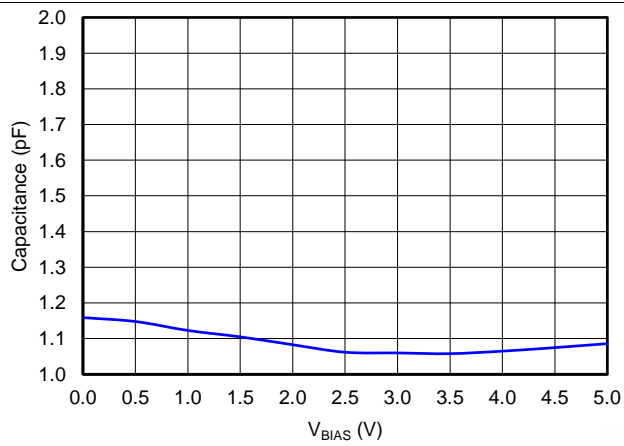


Figure 7. Capacitance vs V_{BIAS}

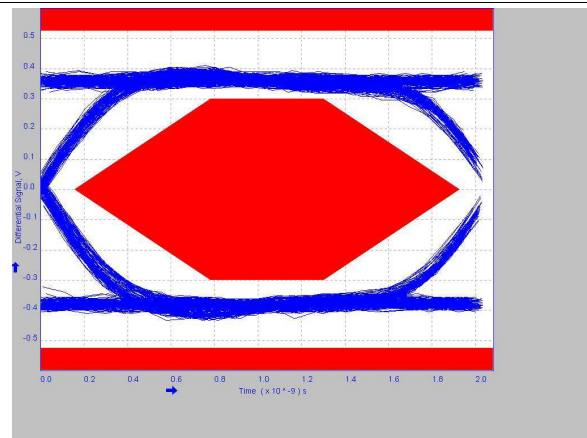


Figure 8. Eye Diagram Without TPD2E1B06DRL on EVM

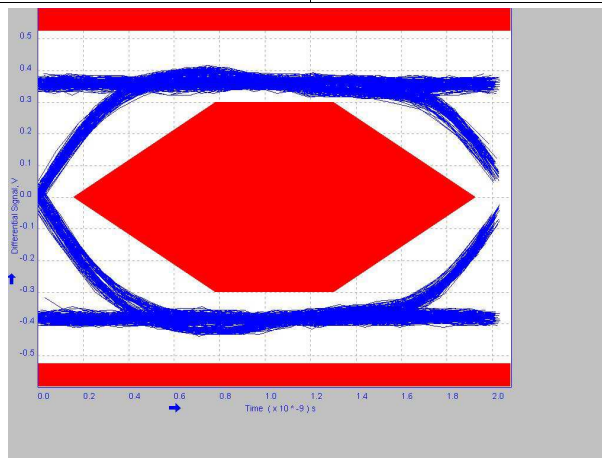


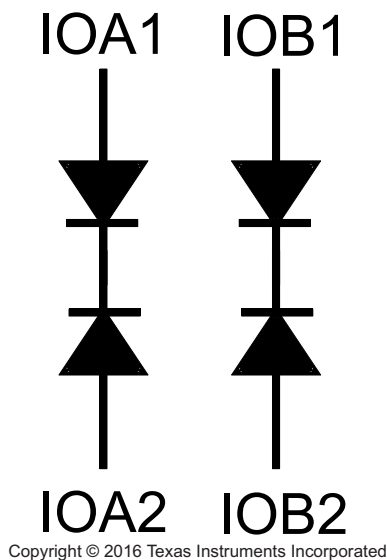
Figure 9. Eye Diagram With TPD2E1B06DRL on EVM

7 Detailed Description

7.1 Overview

The TPD2E1B06 is a bidirectional, low-capacitance, two-channel ESD clamping device. It has more than IEC 61000-4-2 Level 4 ESD Rating. The low IO capacitance makes the device a good fit for a wide range of data speeds. Common applications include USB 2.0, LVDS, and I2C.

7.2 Functional Block Diagram



7.3 Feature Description

The TPD2E1B06 device provides robust system level IEC protection. This device protects circuit from ESD strikes up to ± 10 -kV contact and ± 15 -kV air-gap specified in the IEC 61000-4-2 level 4. It also handles up to 2.5-A surge current (IEC61000-4-5 8/20 μ s). The I/O capacitance of 0.85 pF supports high data rates. The device has a small dynamic resistance of 0.9 Ω , making clamping voltage low when the device is actively protecting other circuits. With low capacitance and dynamic resistance, the TPD2E1B06 is a good fit for interfaces like USB 2.0, LVDS, and I2C. The breakdown is bidirectional so that this protection device is especially good for bidirectional signals like audio lines. Low leakage allows the diode to conserve power when working below the V_{RWM} . The temperature range of -40°C to 125°C makes this ESD device work at extensive temperatures in most environments.

7.4 Device Functional Modes

The TPD2E1B06 is a passive clamp that has low leakage during normal operation when the voltage across each channel is below V_{RWM} and activates when the it goes above V_{BR} . During IEC ESD events, transient voltages will be clamped. When the voltages on the protected lines fall below the trigger voltage, the device reverts back to the low-leakage passive state.

8 Application and Implementation

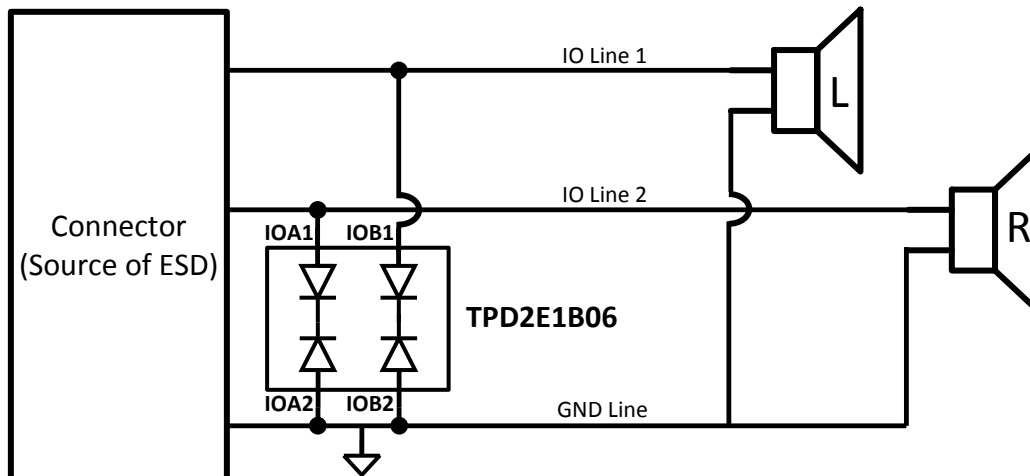
NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

When a system contains a human interface connector, the system becomes vulnerable to large system-level ESD strikes that standard ICs cannot survive. TVS ESD protection diodes are typically used to suppress ESD at these connectors. There are 2 channels of back-to-back diodes in TPD2E1B06. The device is typically used to provide a path to ground for dissipating ESD events between a human interface connector and a system. As the current from ESD passes through the device, only a small voltage drop is present across the diode structure. This is the voltage presented to the protected IC. The low R_{DYN} of the triggered TVS holds this voltage, V_{CLAMP} , to a tolerable level to the protected IC.

8.2 Typical Application



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Figure 10. Typical Application Schematic

8.2.1 Design Requirements

In this design example, a TPD2E1B06 is used to protect audio channels. [Table 1](#) lists the system parameters.

Table 1. Design Parameters

DESIGN PARAMETER	VALUE
Audio Amplifier Class	AB
Audio signal voltage range	–3 V to 3 V
Audio frequency content	20 Hz to 20 kHz
Required IEC 61000-4-2 ESD Protection	±8-kV Contact/ ±15-kV Air-Gap

8.2.2 Detailed Design Procedure

For some parameters, the designer must ensure the following before designing:

- Voltage range on the protected line must not exceed the reverse standoff voltage of the TVS diode(s) (V_{RWM})
- Operating frequency is supported by the I/O capacitance C_{IO} of the TVS diode

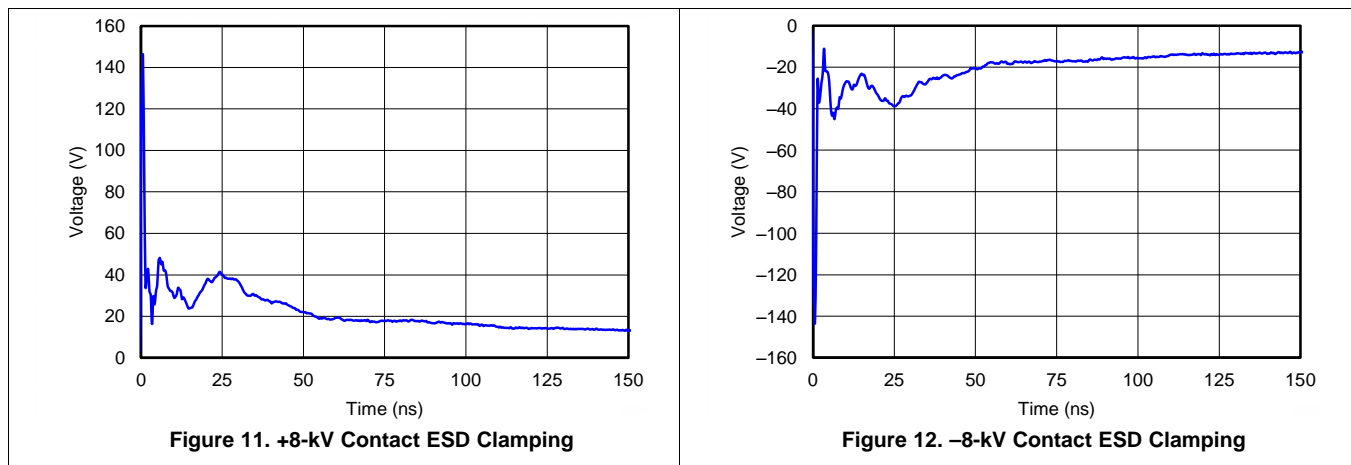
- IEC 61000-4-2 protection requirement is covered by the IEC performance of the TVS diode

For this application, the audio signal voltage range is -3 V to 3 V . The V_{RWM} for the TVS is -5.5 V to 5.5 V ; therefore, the bidirectional TVS will not break down during normal operation.

Next, consider the frequency content of this audio signal. In this application with the class AB amplifier, the frequency content is from 20 Hz to 20 kHz ; ensure that the TVS I/O capacitance will not distort this signal by filtering it. With TPD2E1B06 typical capacitance of 0.85 pF , which leads to a typical 3-dB bandwidth of more than 3 GHz , this diode has way sufficient bandwidth to pass the audio signal without distorting it.

Finally, the human interface in this application requires above standard Level 4 IEC 61000-4-2 system-level ESD protection ($\pm 8\text{-kV}$ Contact and $\pm 15\text{-kV}$ Air-Gap). TPD2E1B06 can survive at least $\pm 10\text{-kV}$ Contact and $\pm 15\text{-kV}$ Air-Gap. Therefore, the device can provide sufficient ESD protection for the interface, even though the requirements are stringent. For any TVS diode to provide the full range of ESD protection capabilities, as well as to minimize the noise and EMI disturbances the board will see during ESD events, a system designer must use proper board layout of their TVS ESD protection diodes. See [Layout](#) for instructions on properly laying out the TPD2E1B06.

8.2.3 Application Curves



9 Power Supply Recommendations

This TPD2E1B06 is a passive TVS diode-based ESD protection device so it does not have any power requirements. Take care not to violate the maximum voltage specifications for each pin.

10 Layout

10.1 Layout Guidelines

- The optimum placement of the TPD2E1B06 is as close to the connector as possible. EMI during an ESD event can couple from the trace being struck to other nearby unprotected traces, resulting in early system failures. The printed-circuit board (PCB) designer must minimize the possibility of EMI coupling by keeping any unprotected traces away from the protected traces, which are between the TVS and the connector.
- Route the protected traces as straight as possible.
- Avoid sharp corners on the protected traces. Electric fields tend to build up on corners, increasing EMI coupling.
- Use thick and short traces for the ground pins

10.2 Layout Examples

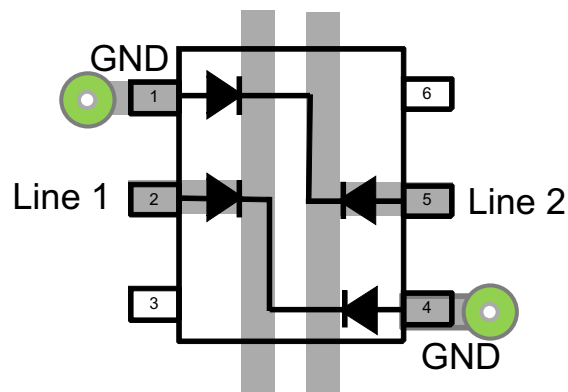


Figure 13. Routing Option 1

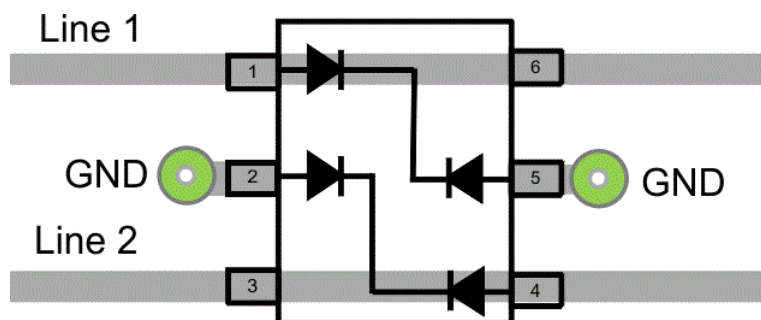


Figure 14. Routing Option 2

11 Device and Documentation Support

11.1 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.2 Trademarks

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11.3 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

11.4 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPD2E1B06DRLR	ACTIVE	SOT-OTHER	DRL	6	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		(DUH ~ DUL)	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

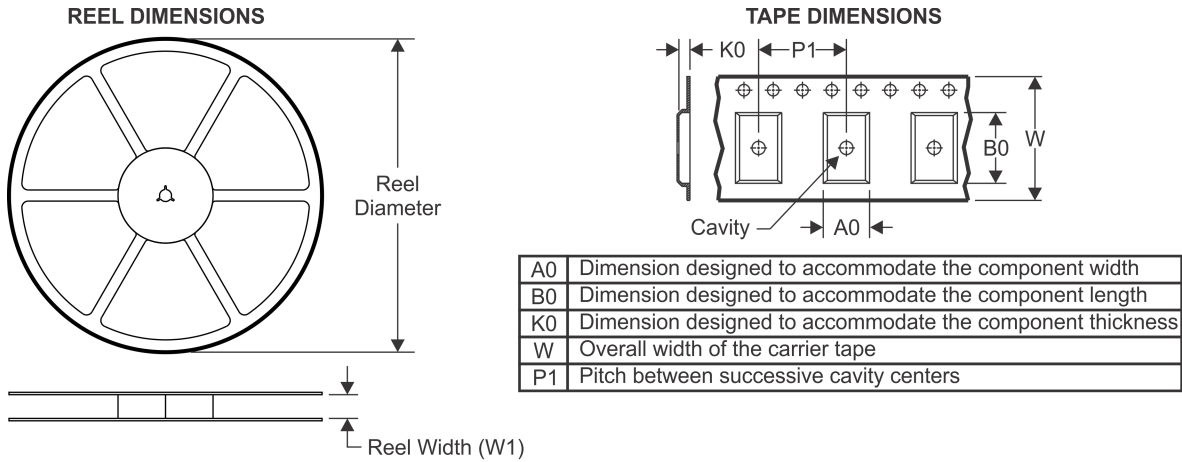
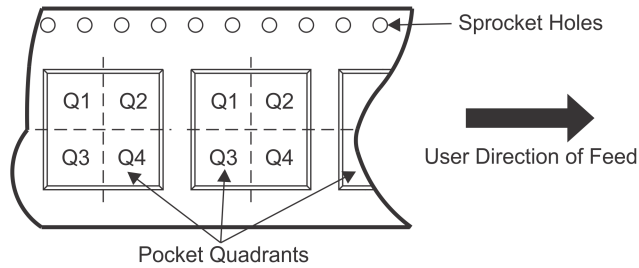
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPD2E1B06DRLR	SOT-OTHER	DRL	6	4000	180.0	9.5	1.78	1.78	0.69	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS

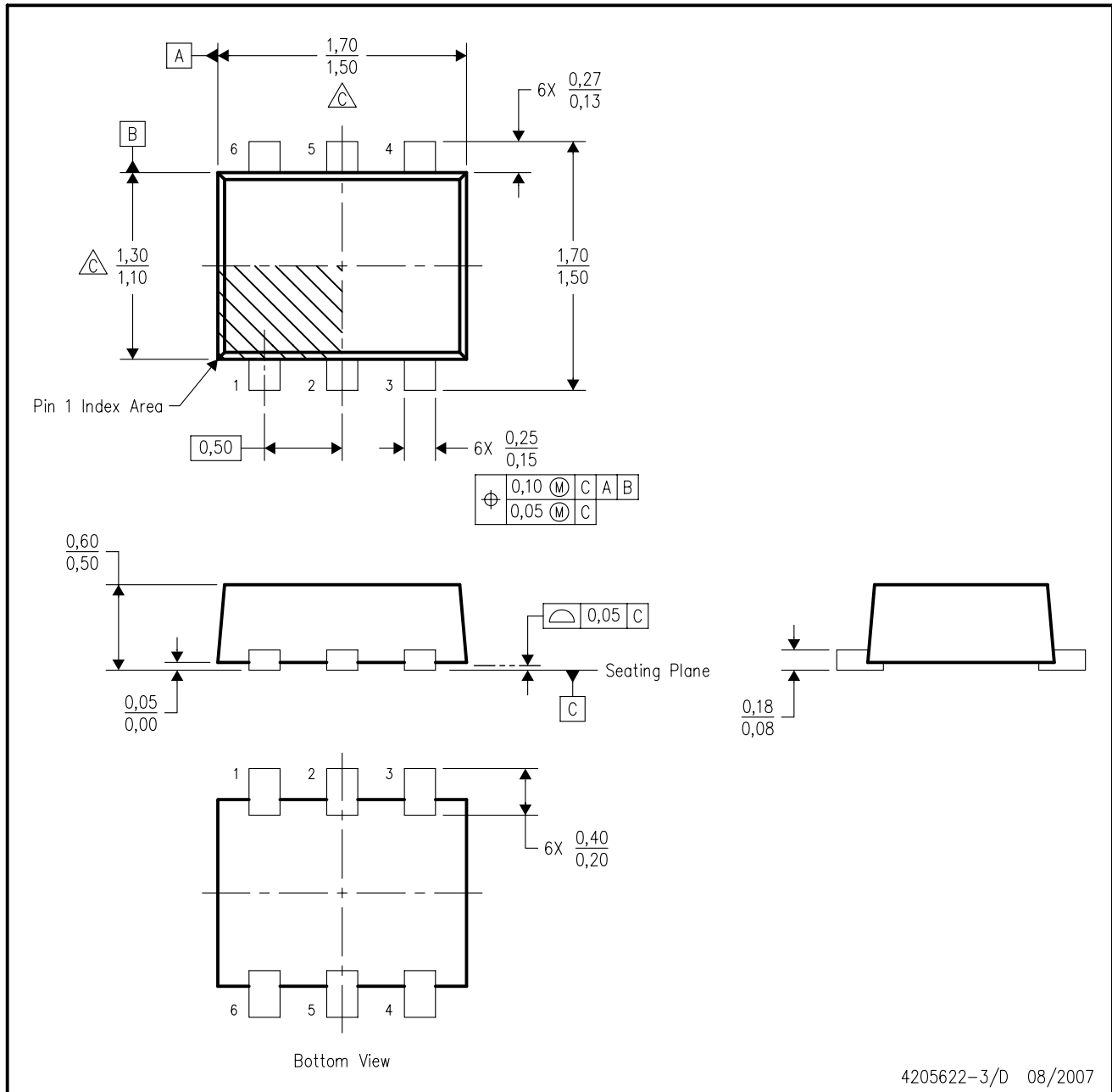



*All dimensions are nominal

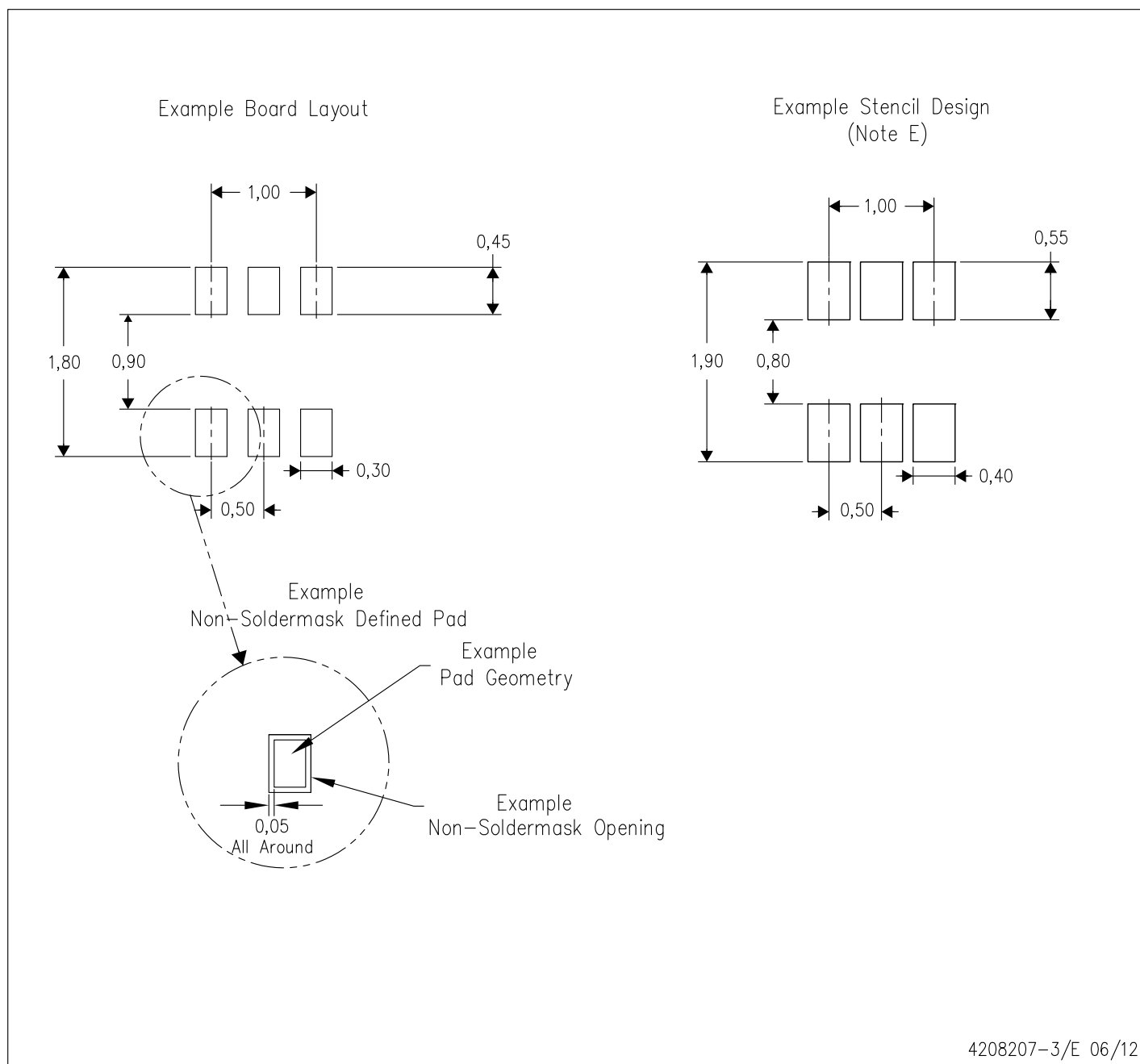
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPD2E1B06DRLR	SOT-OTHER	DRL	6	4000	184.0	184.0	19.0

DRL (R-PDSO-N6)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 -  C. Body dimensions do not include mold flash, interlead flash, protrusions, or gate burrs. Mold flash, interlead flash, protrusions, or gate burrs shall not exceed 0,15 per end or side.
 - D. JEDEC package registration is pending.



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
 - E. Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
 - F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - G. Side aperture dimensions over-print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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